Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V_{DSS}	-20	V
Gate-Source Voltage			V_{GSS}	-12	V
Continuous Drain Current (Note 5) V_{GS} = -8V	Steady State	T_A = +25°C T_A = +70°C	I_D	-3.4 -2.7	A
Continuous Drain Current (Note 5) V_{GS} = -4.5V	Steady State	T_A = +25°C T_A = +70°C	I_D	-3.0 -2.4	A
Pulsed Drain Current (Note 6)			I_{DM}	-13	A
Human Body Model (HBM)			$V_{(ESD)}$	4	kV

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	P_D	0.81	W
Thermal Resistance, Junction to Ambient @T_A = +25°C (Note 7)	$R_{\theta JA}$	155.4	°C/W
Power Dissipation (Note 5)	P_D	1.4	W
Thermal Resistance, Junction to Ambient @T_A = +25°C (Note 5)	$R_{\theta JA}$	90.4	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV_{DSS}	-20	—	—	V	V_{GS} = 0V, I_D = -250µA
Zero Gate Voltage Drain Current T_J = +25°C	I_{DSS}	—	—	-100	nA	V_{DS} = -16V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	-50	nA	V_{GS} = -12V, V_{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	$V_{GS(TH)}$	-0.7	-0.9	-1.2	V	V_{DS} = V_{GS}, I_D = -250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	64	78	mΩ	V_{GS} = -8V, I_D = -0.5A
		—	77	100		V_{GS} = -4.5V, I_D = -0.5A
		—	113	165		V_{GS} = -2.5V, I_D = -0.5A
		—	188	600		V_{GS} = -1.8V, I_D = -0.1A
Diode Forward Voltage	V_{SD}	—	-0.7	-1.0	V	V_{GS} = 0V, I_S = -0.5A
Reverse Recovery Charge	Q_{RR}	—	1.3	—	nC	V_{DD} = -10V, I_F = -1A, di/dt = 100A/µs
Reverse Recovery Time	t_{RR}	—	7.7	—	ns	
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	—	152	228	pF	V_{DS} = -10V, V_{GS} = 0V, f = 1MHz
Output Capacitance	C_{oss}	—	78	117		
Reverse Transfer Capacitance	C_{rss}	—	4.3	6.4		
Series Gate Resistance	R_G	—	21	31	Ω	f = 1MHz, V_{GS} = 0V, V_{DS} = 0V
Total Gate Charge	Q_g	—	1.1	1.6	nC	V_{GS} = -4.5V, V_{DS} = -10V, I_D = -0.5A
Gate-Source Charge	Q_{gs}	—	0.2	—		
Gate-Drain Charge	Q_{gd}	—	0.2	—		
Gate Charge at V_{TH}	$Q_{g(th)}$	—	3.6	—		
Turn-On Delay Time	$t_{D(ON)}$	—	4.1	6.1	ns	V_{DS} = -10V, V_{GS} = -4.5V, R_G = 2Ω, I_D = -0.5A
Turn-On Rise Time	t_R	—	5.6	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	9.5	14.2		
Turn-Off Fall Time	t_F	—	4.6	—		

Notes:
5. Device mounted on FR-4 material with 1inch^2 (6.45cm^2), 2oz. (0.071mm thick) Cu.
6. Repetitive rating, pulse width limited by junction temperature.
7. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to production testing.

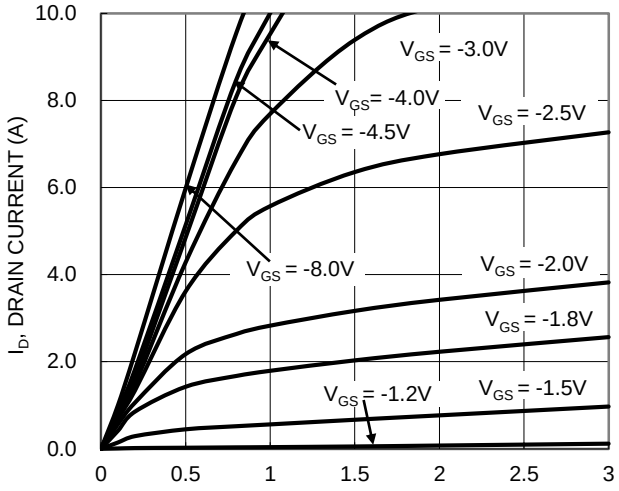

Figure 1. Typical Output Characteristic

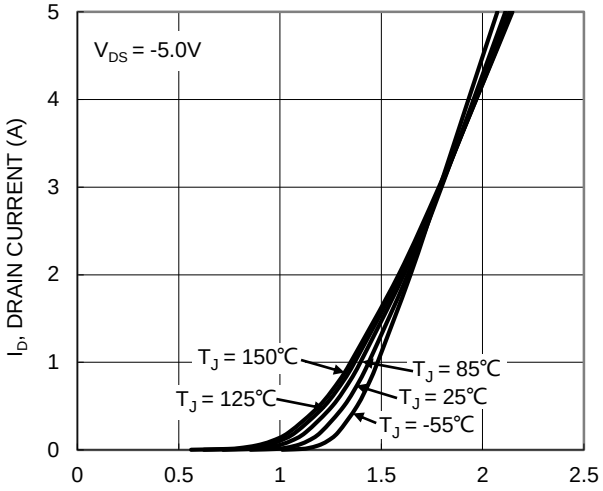

Figure 2. Typical Transfer Characteristic

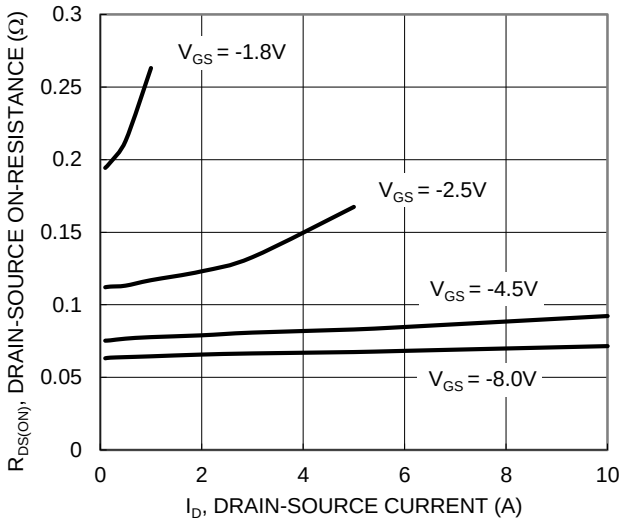

Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

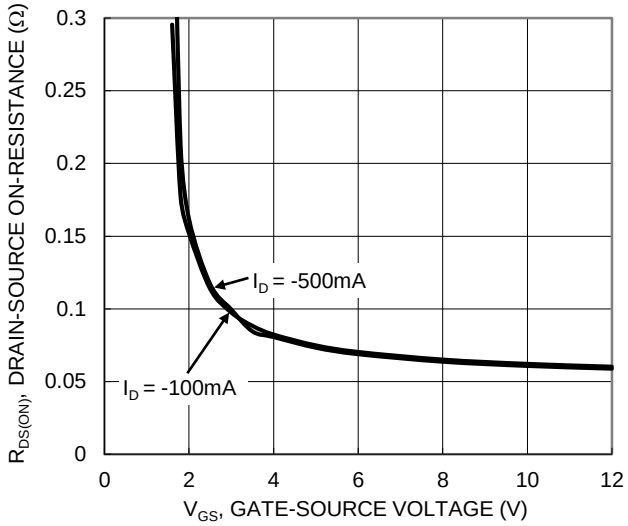

Figure 4. Typical Transfer Characteristic

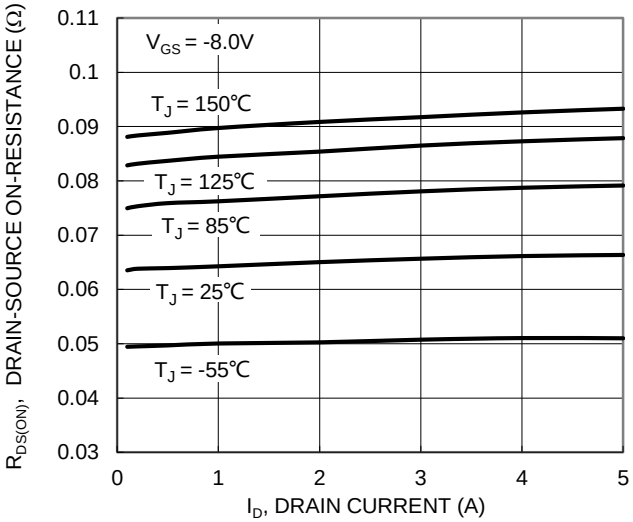

Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

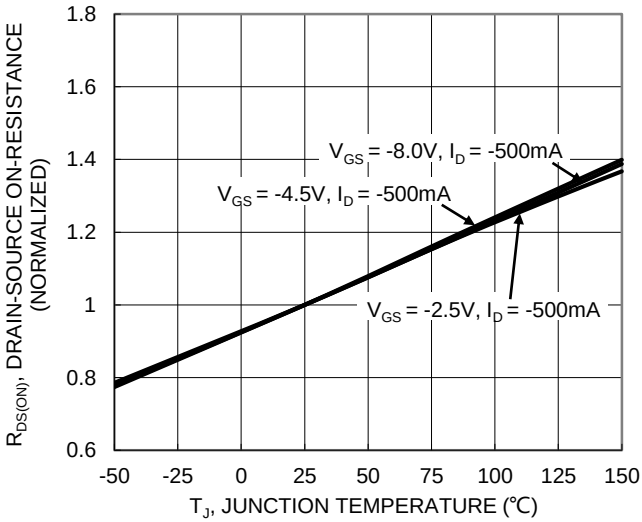

Figure 6. On-Resistance Variation with Junction Temperature

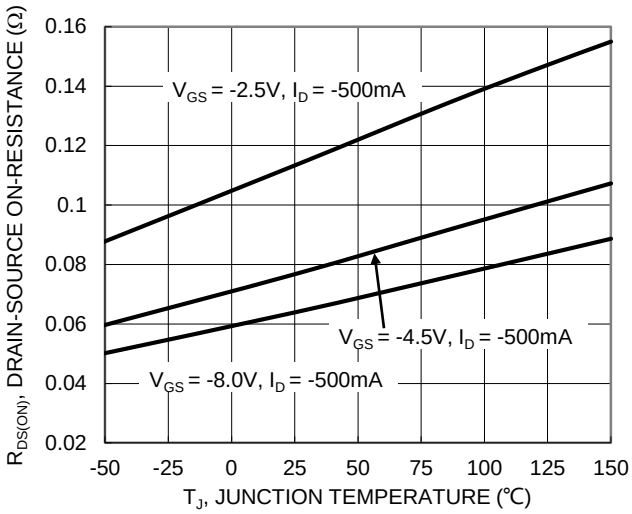

Figure 7. On-Resistance Variation with Junction Temperature

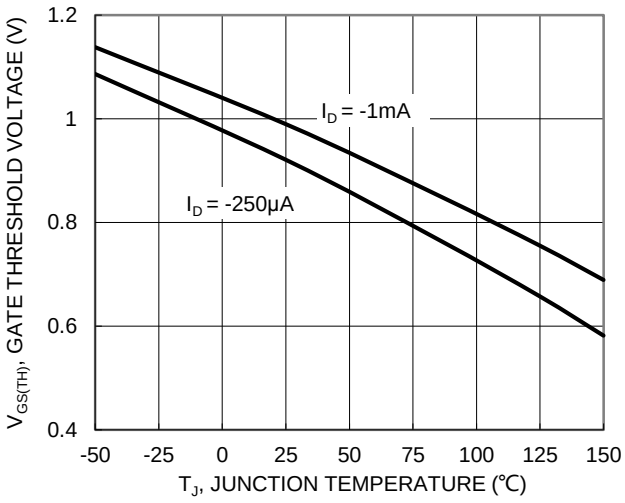

Figure 8. Gate Threshold Variation vs. Junction Temperature

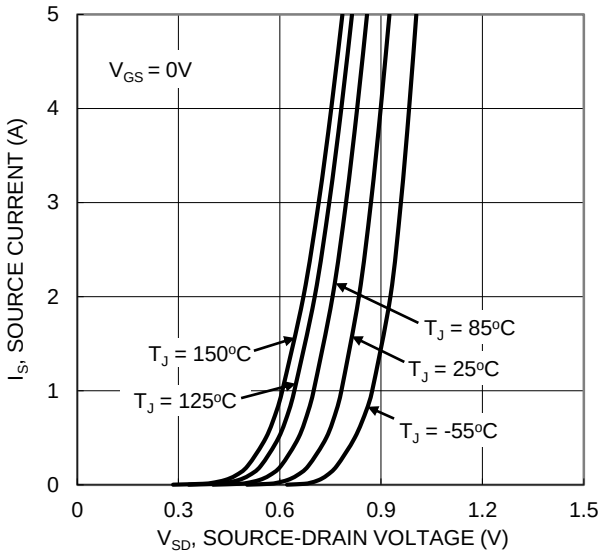

Figure 9. Diode Forward Voltage vs. Current

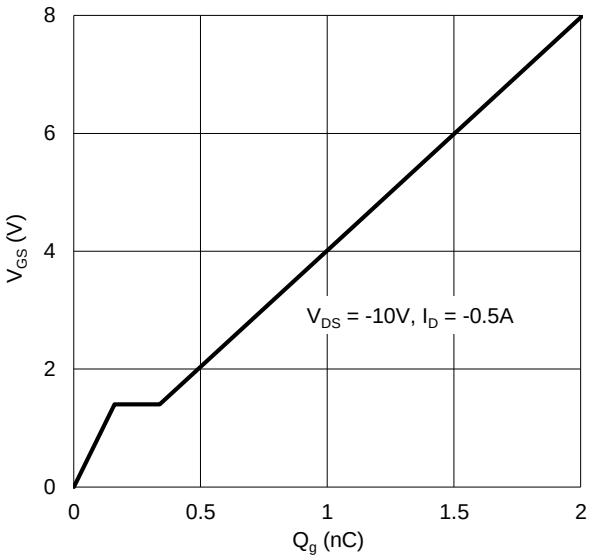

Figure 10. Gate Charge

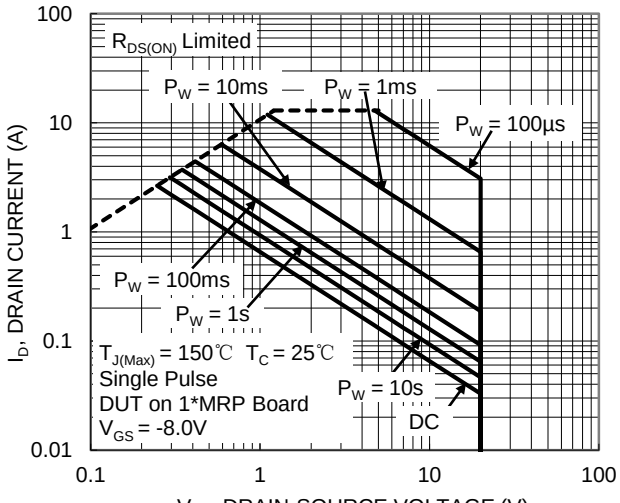

Figure 11. SOA, Safe Operation Area

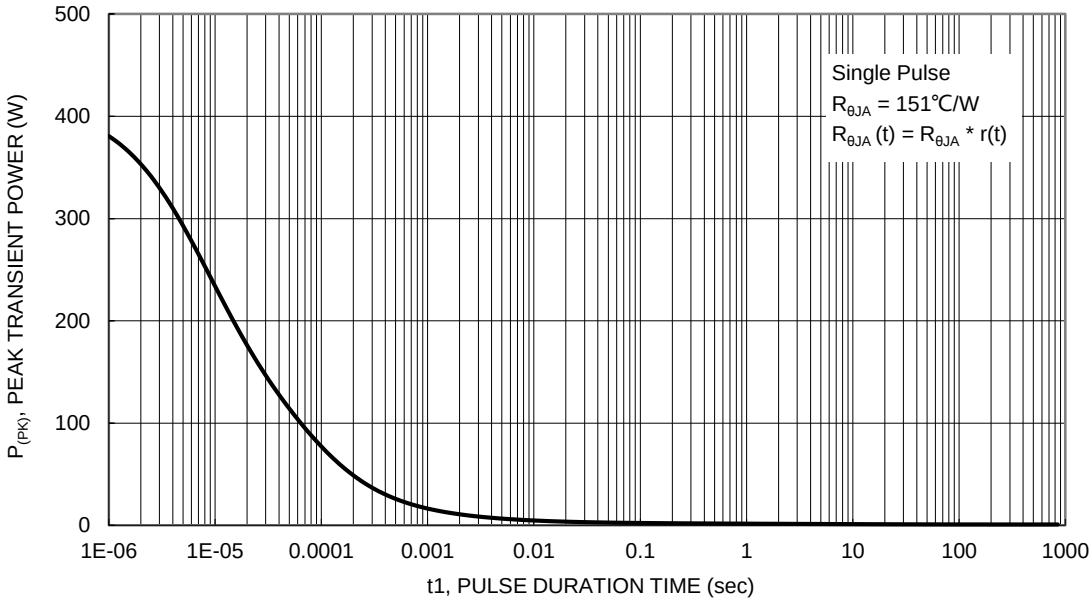

Figure 12. Single Pulse Maximum Power Dissipation

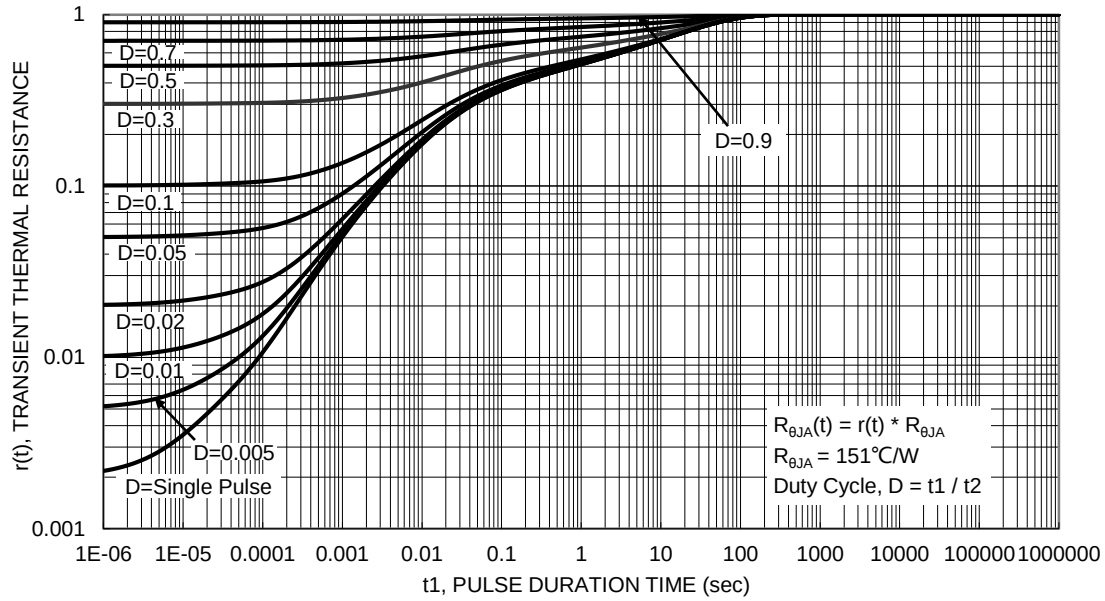

Figure 13. Transient Thermal Resistance

Package Outline Dimensions

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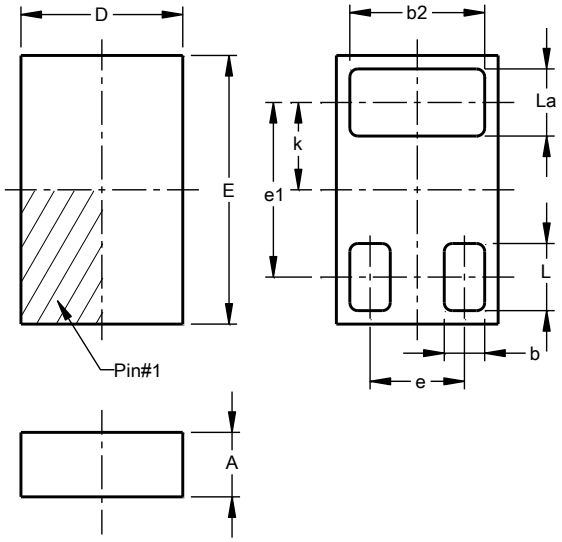
X4-DSN1006-3

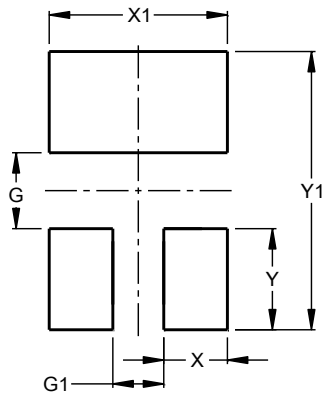


X4-DSN1006-3			
Dim	**Min**	**Max**	**Typ**
A	0.18	0.22	0.20
b	0.14	0.16	0.15
b2	0.49	0.51	0.50
D	0.56	0.64	0.60
E	0.96	1.04	1.00
e	--	--	0.35
e1	--	--	0.65
k	--	--	0.325
L	0.24	0.26	0.25
La	0.24	0.26	0.25
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X4-DSN1006-3



Dimensions	Value (in mm)
G	0.40
G1	0.20
X	0.15
X1	0.50
Y	0.25
Y1	0.90

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